

Final Product/Process Change Notification Document #:FPCN25004X1

Issue Date:04 Jul 2022

Title of Change:	Update to FPCN25004X - to adjust Proposed First Ship Date to September, 5th, 2023		
Proposed First Ship date:	05 Sep 2023 or earlier if approved by customer		
Contact Information:	Contact your local onsemi Sales Office or Huan.Tran@onsemi.com		
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onsemi Sales Office or Lalan.Ortega@onsemi.com		
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Identify by Lot code.		
Change Category:	Assembly Change		
Change Sub-Category(s):	Material Change		
Sites Affected:	ites Affected:		
onsemi Sites		External Foundry/Subcon Sites	
None		SHANTOU HUASHAN Electronic Devices Co., Ltd., China	

Description and Purpose:

Update to FPCN25004X - to adjust Proposed First Ship Date to September 5th, 2023.

onsemi wishes to inform a change in mold compounds used for the devices listed in this PCN due to potential end of life of part EME6600CS S4L by end of 2023. There is no product marking change as a result of this change.

	From	То
Mold Compound	EME6600CS S4L, SUMITOMO	KTMC1050GFA, KCC

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Reliability Data Summary:

QV DEVICE NAME FGH30N60LSDTU

RMS: U86642 PACKAGE: TO-247-3

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0 / 231
High Temperature Gate Bias	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0 / 231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0 / 231
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C, On/off = 5.0 mins	6000 cyc	0 / 120
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0 / 231
High Humidity, High Temperature Reverse Bias	JEDS22 A101	Ta = 85°C, 85% RH, bias	1008 hrs	0 / 231
Unbiased Highly Accelerated Stress Test	JESD22-A118	Ta = 130°C, 85% RH, 18.8psig, unbiased	96 hrs	0 / 231
Resistance to Solder Heat	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only		0 / 90

Electrical Characteristics Summary:

Electrical characteristics are not impacted

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FGH20N60SFDTU	HGTG40N60A4
FGH40N60SFDTU	HGTG40N60A4

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